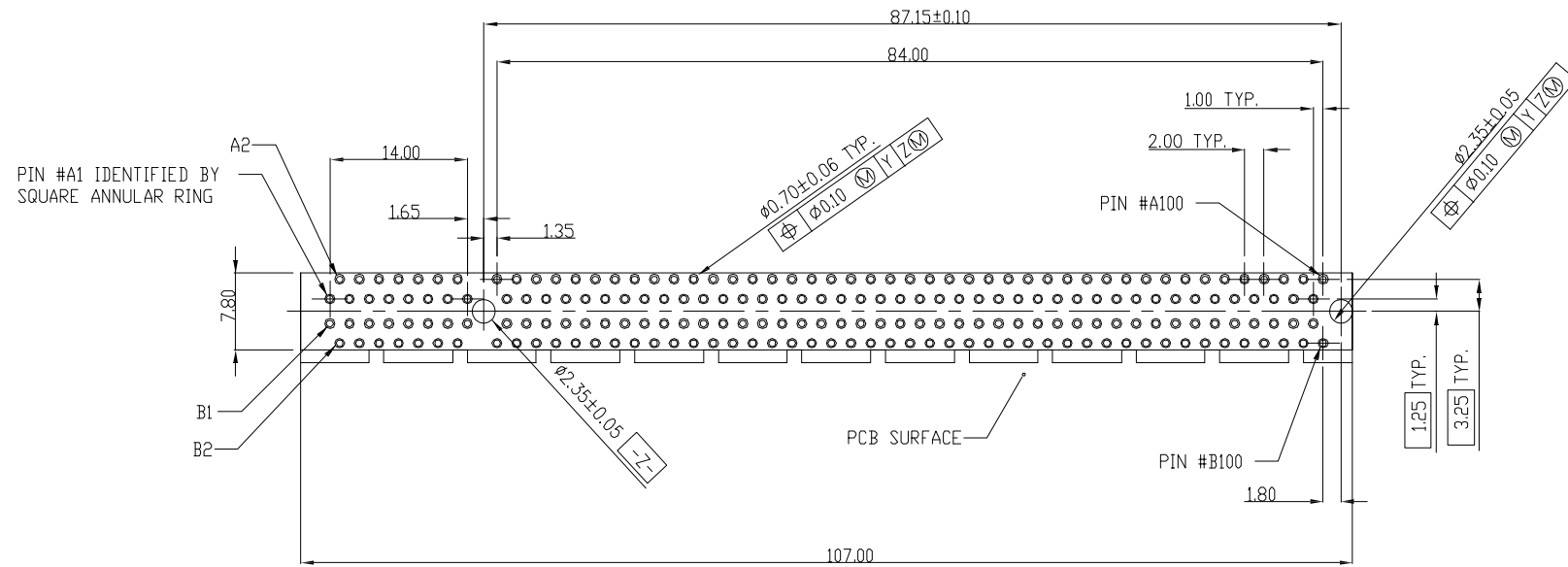
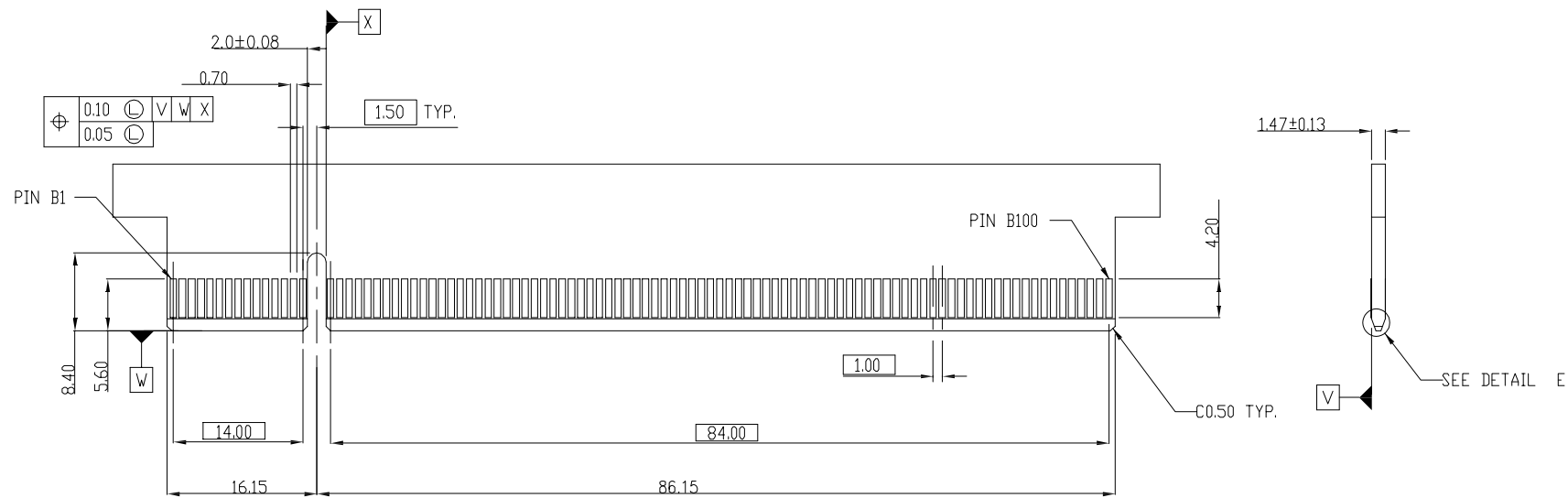


B

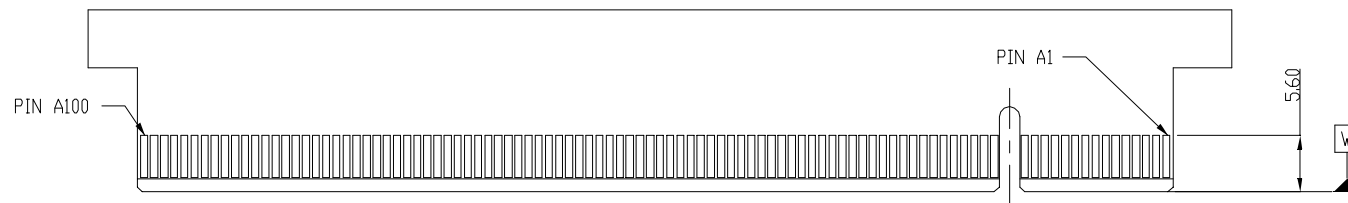


MOTHER BOARD FOOTPRINT PATTERN
CONECTOR SIDE SHOWN

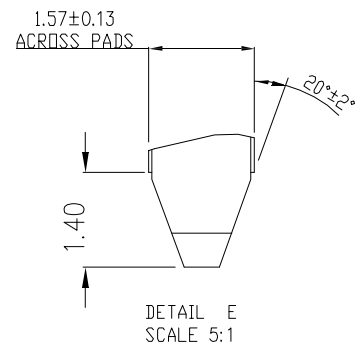
mat'l. code				tolerances unless otherwise specified			CUSTOMER COPY		 www.fciconnect.com		
ltr	ecn no	dr	date	linear	.X ±.38		projection 	title PCI-E 200P CARD EDGE GEN3 			
					.XX ±.25						
					.XXX ±.10						
				angles	0° ±2°		 MM	product family		PCI	code
				dr	STONE LI	05/27/15		size		dwg no	—
				enrg	STONE LI	05/27/15		sheet		2 of 4	
				chr	/	/	scale	A4		10054652	
				appd	PM ZHENG	05/27/15	N/A				
sheet index	revision sheet										

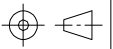


← I/O PANEL DIRECTION
PRIMARY (COMPONENT) SIDE



→ I/O PANEL DIRECTION
SECONDARY (SOLDER) SIDE



mat'l. code				tolerances unless otherwise specified			CUSTOMER COPY	 www.fciconnect.com		
ltr	ecn no	dr	date	linear	.X ±.38	.XX ±.25				
					.XXX ±.10	0° ±2°	projection	 MM		
				angles						
				dr	STONE LI	05/27/15	scale	product family PCI size dwg no A4 10054652		
				enrg	STONE LI	05/27/15				
				chr	/	/	N/A	code — sheet 3 of 4		
				appd	PM ZHENG	05/27/15				
sheet index	revision sheet									

cage code
22526

NOTES:

1.MATERIAL:

HOUSING: THERMOPLASTIC WITH GLASS FIBER, UL94V-0,
COLOR IN BLACK.
CONTACTS: COPPER ALLOY.

2.FINISH:

CONTACTS: GOLD PLATING ON CONTACT AREA,
100 μ MIN. TIN/LEAD OR MATTE TIN (LEAD FREE OPTION) PLATING ON SOLDER TAILS,
50 μ MIN. NICKEL UNDERPLATING OVER ALL.
BOARDLOCKS: 100 μ TIN/LEAD OR MATTE TIN (LEAD FREE OPTION) PLATING ON SOLDER TAILS,
50 μ MIN. NICKEL UNDERPLATING OVER ALL.

3. DURABILITY: 50 CYCLES.

4. RoHS COMPATIBLE PRODUCT SPECIFICATIONS

- a. PLATING: "LF" MEANS THE PRODUCT IS LEAD FREE, 2.5um min. MATTE PURE TIN OVER 1.27um MIN. NICKEL UNDERPLATE.
- b. MANUFACTURING PROCESS COMPATIBILITY: THE HOUSING WILL WITHSTAND EXPOSURE TO 260C $\pm$ 5C $\pm$ SOLDER BATH TEMPERATURE FOR 5 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.60MM THICK CIRCUIT BOARD.

PRODUCT NUMBER CODE

10054652 - X X X X X X LF

HOUSING COLOR OPTIONS
1-BLACK

PEGS OPTIONS
0-PLASTIC PEGS

TERMINAL PLATING OPTIONS
0-50 μ Ni UNDERPLATE
30 μ Au CONTACT AREA
100 μ TIN TAIL AREA -----COMPATIBLE RoHS
1-50 μ Ni UNDERPLATE
15 μ Au CONTACT AREA
100 μ TIN TAIL AREA -----COMPATIBLE RoHS
2-50 μ Ni UNDERPLATE
GOLD FLASH CONTACT AREA
100 μ TIN TAIL AREA -----COMPATIBLE RoHS

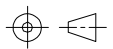
LEAD FREE

PACKAGING OPTIONS
T-TRAY PACKAGING

RESERVE
0

TAIL LENGTH OPTIONS

	DIM "D"	SUGGESTED PCB THICKNESS
1	3.10	2.36 $\pm$ 0.10
2	2.54	1.56 $\pm$ 0.10

mat'l. code				tolerances unless otherwise specified		CUSTOMER COPY	 www.fciconnect.com	
ltr	ecn no	dr	date	linear	.X $\pm$.38			
					.XX $\pm$.25			
					.XXX $\pm$.10			
				angles	0 $^{\circ}$ $\pm$ 2 $^{\circ}$	 MM	 N/A	title PCI-E 200P CARD EDGE GEN3 
				dr	STONE LI 05/27/15			
				enrg	STONE LI 05/27/15			
				chr	/ /			
				appd	PM ZHENG 05/27/15	product family PCI	size A4	code 10054652
sheet	revision							
index	sheet							

cage code
22526